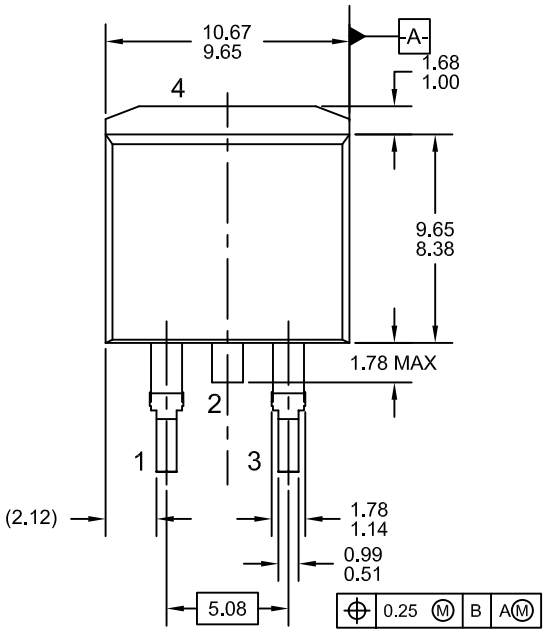
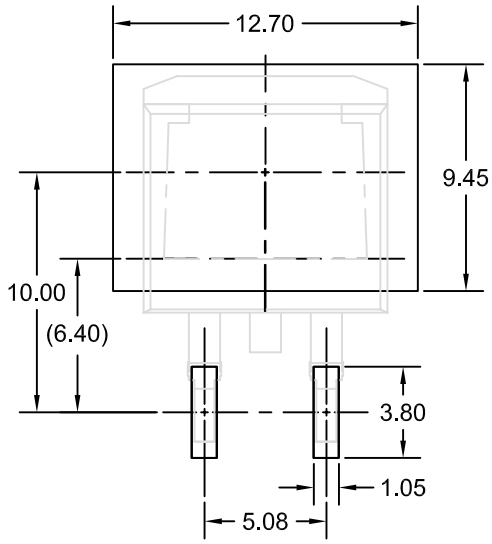
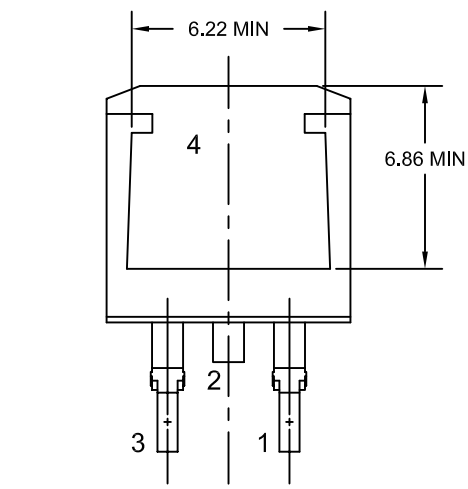
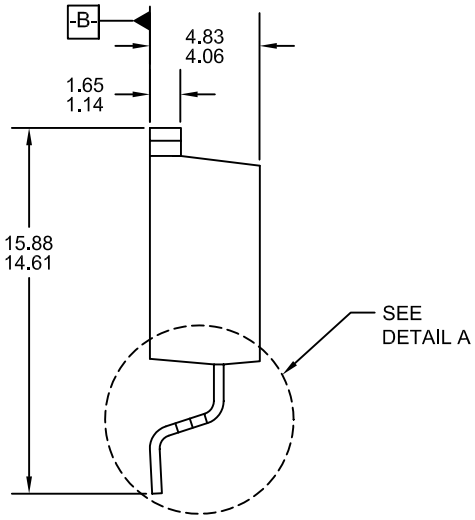
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	CB/085/99	08NOV1999	MRG
B	CHG HEATSINK DIM FR 1.27/.05 TO 1.50/.05; PKG DIM FR 5.04/.04 TO 5.01/.01; LD CUT FR 1.35/.05 TO 1.77/.05; ADD DIM (2,12); CHG TER 4 FR 5.37/.07 TO (8,00), FR 6.45/.05 TO (7,20); TOT LGH FR 10.28/.05 TO 10.00/.05; ADD DETAIL A: CHG LD THICK FR 5.56/.06 TO 5.08/.05; CHG FOOT LGTH FR 1.27/.05 TO 1.52/.05; ADD DIM (5,38); CHG LAND PATTERN DIM FR 9,50 TO 9,50 MIN, FR 9,00 TO 9,00 MIN, FR 4,00 TO 4,00 MIN, FR 1,50 TO 1,50 MIN; DEL NOTE C&D AND ARRANGE, ADD NOTE D.	CB/044/00	28FEB2000	MRG
C	CHG CEN LD CUT FR 1.27/.05 TO 1.78 MAX; LD WID FR 1.70/.05 TO 5.08/.01; PKG THICK FR 4.83/.05 TO 4.06/.05; HEAT SINK THICK FR 1.40/.05 TO 1.65/.05; LD THICK FR 5.08/.05 TO 5.18/.05; FOOT LANDING FR 2.54/.05 TO 2.79/.05; FOOT ANGLE FR 3/.5 TO 3/.5 DEG; PROFILE DIM FR 0,13 MAX TO 0,25 MAX; BACK HEAT SINK WID FR (8,00) TO 6,22 MIN, LEN FR (7,20) TO 6,86 MIN; REMOVE EJECTOR PIN MARK; ADD NOTE E	CB/254/04	7OCT2004	RCM
D	REMOVE NOTE B; ADD NOTE E	CB/043/05	30MAR2005	MRG
5	REMOVED SITE INFO AND ECN COLUMN, ADDED NOTE F, TITLE CHANGED		06AUG2007	H.ALLEN
6	UPDATED HEATSINK PER IPC STANDARD, NOTE E IPC REFERENCE, FONT TO ARIAL, UPDATED DRAWING TITLE TO REFLECT JEDEC STANDARD.		02 MAY 09	H.ALLEN



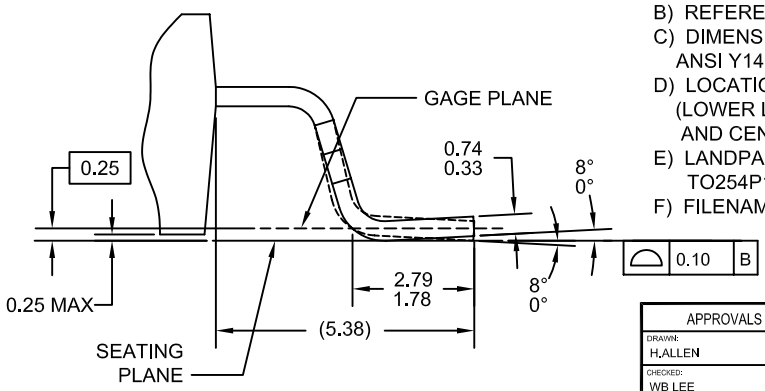


LAND PATTERN RECOMMENDATION
UNLESS NOTED, ALL DIMS TYPICAL





NOTES: UNLESS OTHERWISE SPECIFIED
A) ALL DIMENSIONS ARE IN MILLIMETERS.
B) REFERENCE JEDEC, TO-263, VARIATION AB.
C) DIMENSIONING AND TOLERANCING PER ANSI Y14.5M - 1994.
D) LOCATION OF THE PIN HOLE MAY VARY (LOWER LEFT CORNER, LOWER CENTER AND CENTER OF THE PACKAGE).
E) LANDPATTERN RECOMMENDATION PER IPC TO254P1524X482-3N
F) FILENAME: TO263A02REV6



DETAIL A, ROTATED 90°
SCALE: 2X

APPROVALS	DATE
DRAWN: H.ALLEN	2 MAY 09
CHECKED: WB LEE	2 MAY 09
APPROVED:	

FAIRCHILD SEMICONDUCTOR™

2LD, JEDEC TO-263,VARIATION AB,SURFACE MOUNT

PROJECTION
INCH [MM]

SCALE	SIZE	DRAWING NUMBER	REV
1:1	NA	MKT-TO263A02	6

FORMERLY: N/A SHEET: 1 OF 1